

## Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The MPVZ5150 series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This patented, single element transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure.

### Features

- 2.5% Maximum Error over 0° to 85°C
- Ideally suited for Microprocessor or Microcontroller-Based Systems
- Patented Silicon Shear Stress Strain Gauge
- Available in Gauge Surface Mount (SMT) or Through Hole (DIP) Configurations
- Increased media compatibility

## MPVZ5150 Series

0 to 150 kPa (0 to 21.75 psi)  
0.2 to 4.7 V Output

### Typical Applications

- Level Indicators
- Process Control
- Pump/Motor Control
- Pressure Switching

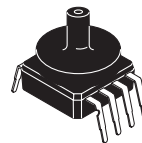
### ORDERING INFORMATION

| Device Name  | Package Options | Case No. | # of Ports |        |      | Pressure Type |              |          | Device Marking |
|--|-----------------|----------|------------|--------|------|---------------|--------------|----------|----------------|
|  |                 |          | None       | Single | Dual | Gauge         | Differential | Absolute |                |
| <b>Small Outline Package (Media Resistant Gel) (MPVZ5150 Series)</b> |                 |          |            |        |      |               |              |          |                |
| MPVZ5150GC6T1  | Tape & Reel     | 482A     |            | •      |      | •             |              |          | MPVZ5150G      |
| MPVZ5150GC7U   | Rail            | 482C     |            | •      |      | •             |              |          | MPVZ5150G      |

### SMALL OUTLINE PACKAGES



MPVZ5150GC6T1  
CASE 482A



MPVZ5150GC7U  
CASE 482C

## Operating Characteristics

**Table 1. Operating Characteristics** ( $V_S = 5.0$  Vdc,  $T_A = 25^\circ\text{C}$  unless otherwise noted,  $P_1 > P_2$ . Decoupling circuit shown in Figure 3 required to meet electrical specifications.)

| Characteristic  | Symbol    | Min   | Typ       | Max   | Unit        |
|---|-----------|-------|-----------|-------|-------------|
| Pressure Range <sup>(1)</sup>                             | $P_{OP}$  | 0     | —         | 150   | kPa         |
| Supply Voltage <sup>(2)</sup>                             | $V_S$     | 4.75  | 5.0       | 5.25  | $V_{DC}$    |
| Supply Current  | $I_O$     | —     | 7.0       | 10    | mAdc        |
| Minimum Pressure Offset <sup>(3)</sup><br>@ $V_S = 5.0$ V | $V_{OFF}$ | 0.088 | 0.200     | 0.313 | $V_{DC}$    |
| Full Scale Output <sup>(4)</sup><br>@ $V_S = 5.0$ V       | $V_{FSO}$ | 4.588 | 4.700     | 4.813 | $V_{DC}$    |
| Full Scale Span <sup>(5)</sup><br>@ $V_S = 5.0$ V         | $V_{FSS}$ | —     | 4.500     | —     | $V_{DC}$    |
| Accuracy <sup>(6)</sup>                                   | —         |       |           |       |             |
| Sensitivity   | V/P       | —     | 30        | —     | mV/kPa      |
| Response Time <sup>(7)</sup>                              | $t_R$     | —     | 1.0       | —     | ms          |
| Output Source Current at Full Scale Output                | $I_{O+}$  | —     | 0.1       | —     | mAdc        |
| Warm-Up Time <sup>(8)</sup>                               | —         | —     | 20        | —     | ms          |
| Offset Stability <sup>(9)</sup>                           | —         | —     | $\pm 0.5$ | —     | % $V_{FSS}$ |

- 1 kPa (kiloPascal) equals 0.145 PSI.
- Device is ratiometric within this specified excitation range.
- Offset ( $V_{OFF}$ ) is defined as the output voltage at the minimum rated pressure.
- Full Scale Output ( $V_{FSO}$ ) is defined as the output voltage at the maximum or full rated pressure.
- Full Scale Span ( $V_{FSS}$ ) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
- Accuracy (error budget) consists of the following:
  - Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.
  - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
  - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from minimum or maximum rated pressure at  $25^\circ\text{C}$ .
  - TcSpan: Output deviation over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .
  - TcOffset: Output deviation with minimum pressure applied over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .
  - Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of  $V_{FSS}$  at  $25^\circ\text{C}$ .
7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
8. Warm-Up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
9. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

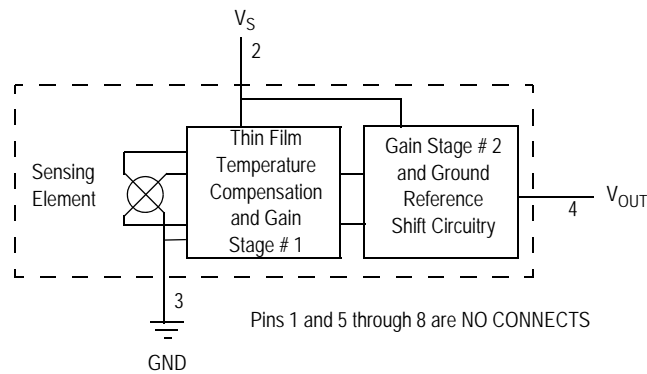
## Maximum Ratings

**Table 2. Maximum Ratings<sup>(1)</sup>**

| Rating                     | Symbol           | Value          | Unit |
|----------------------------|------------------|----------------|------|
| Maximum Pressure (P1 > P2) | P <sub>MAX</sub> | 400            | kPa  |
| Storage Temperature        | T <sub>STG</sub> | -40° to +125°C | °C   |
| Operating Temperature      | T <sub>A</sub>   | -40° to +125°C | °C   |

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.



**Figure 1. Fully Integrated Pressure Sensor Schematic**

## On-chip Temperature Compensation and Calibration

Figure 2 illustrates the Differential/Gauge Sensing Chip in the basic chip carrier (Case 867). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MPVZ5150 series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

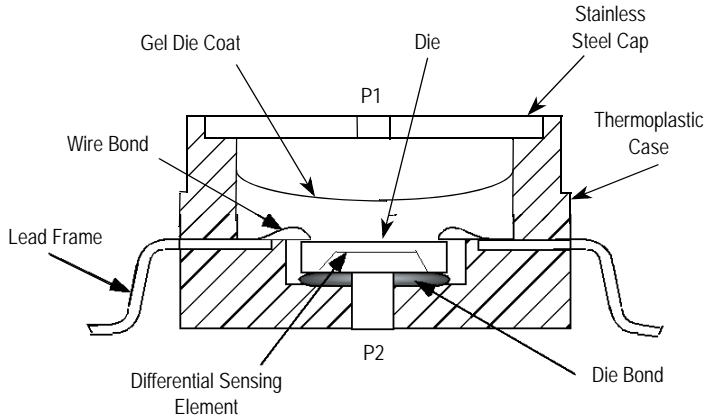


Figure 2. Cross-Sectional Diagram (not to scale)

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range.

Figure 3 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

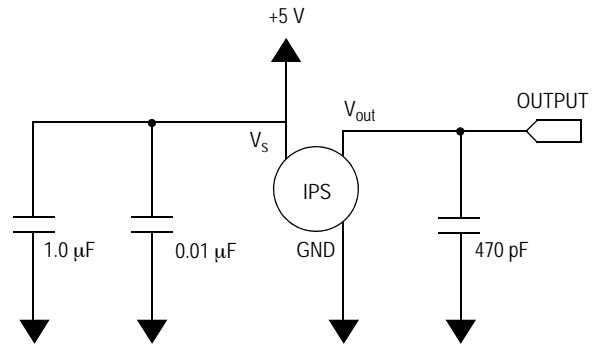


Figure 3. Recommended Power Supply Decoupling and Output Filtering

(For additional output filtering, please refer to Application Note AN1646)

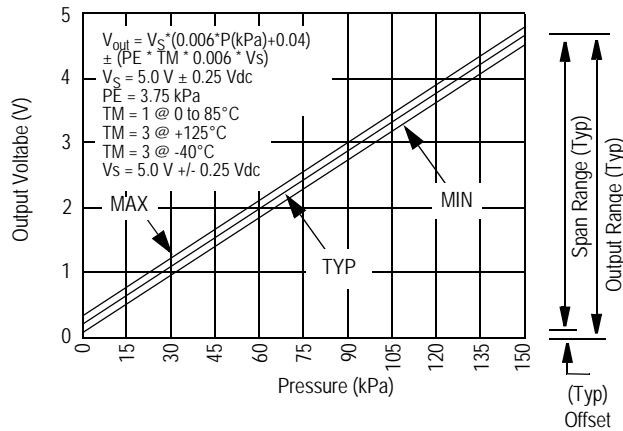


Figure 4. Output vs. Pressure Differential

**Transfer Function (MPVZ5150 Series)**

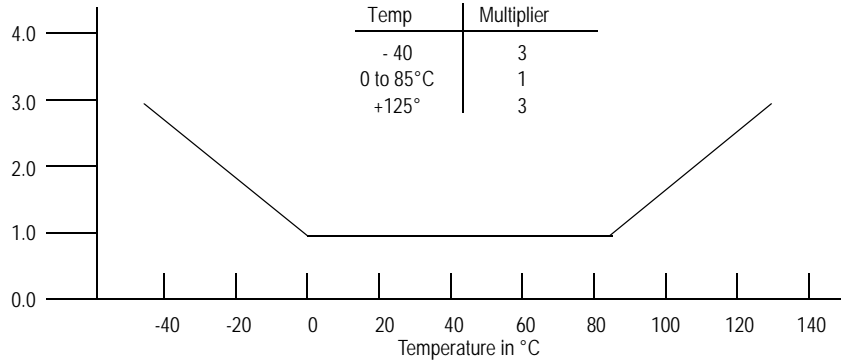
**Nominal Transfer Value:**  $V_{OUT} = V_S \times (0.006 \times P \text{ (kPa)} + 0.04)$   
 $\pm (\text{Pressure Error} \times \text{Temp. Mult.} \times 0.006 \times V_S)$   
 $V_S = 5.0 \text{ V} \pm 0.25 \text{ Vdc}$

**Temperature Error Multiplier**

**MPVZ5150 Series**

Break Points

| Temp      | Multiplier |
|-----------|------------|
| - 40      | 3          |
| 0 to 85°C | 1          |
| +125°     | 3          |

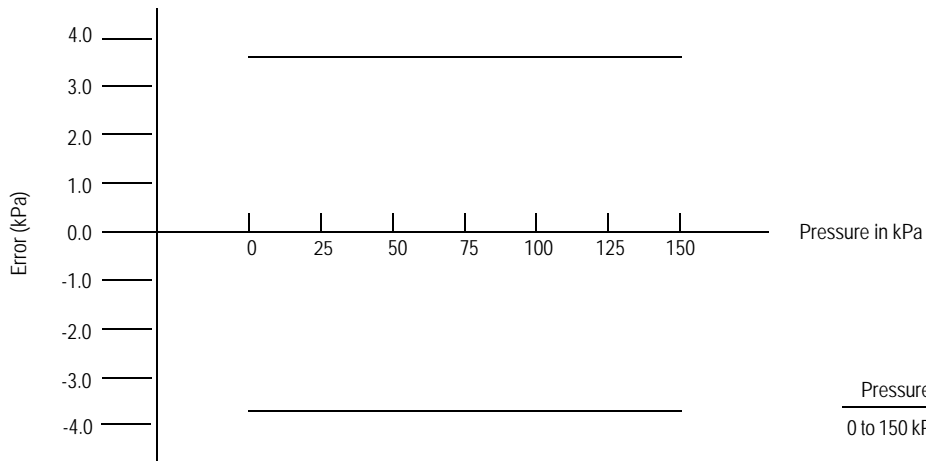


Note: The Temperature Multiplier is a linear response from 0° to -40°C and from 85° to 125°C.

**Pressure Error Band**

**MPVZ5150 Series**

Error Limits for Pressure



| Pressure     | Error (max) |
|--------------|-------------|
| 0 to 150 kPa | ± 3.75 kPa  |

## PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluorosilicone gel which protects the die from harsh media. The MPX pressure

sensor is designed to operate with positive differential pressure applied,  $P1 > P2$ .

The Pressure (P1) side may be identified by using the table below:

| Part Number   | Case Type | Pressure (P1) Side Identifier |
|---------------|-----------|-------------------------------|
| MPVZ5150GC6T1 | 482A      | Side with Port Attached       |
| MPVZ5150GC7U  | 482C      | Side with Port Attached       |

## MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the surface mount packages must be the correct size to ensure proper solder connection interface between the board and the package. With the correct

footprint, the packages will self align when subjected to a solder reflow process. It is always recommended to design boards with a solder mask layer to avoid bridging and shorting between solder.

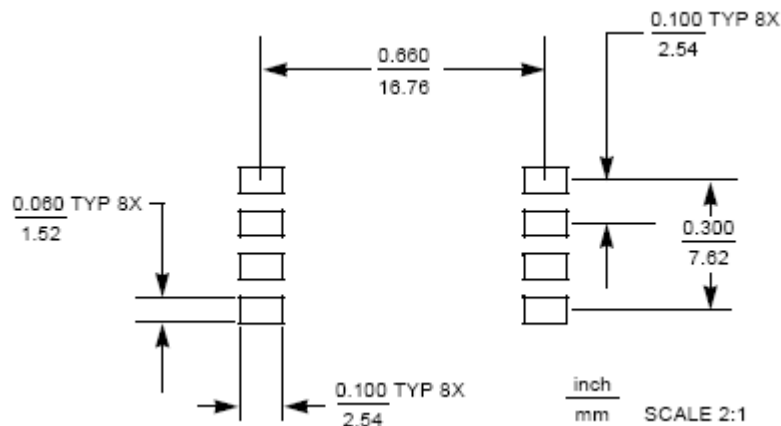
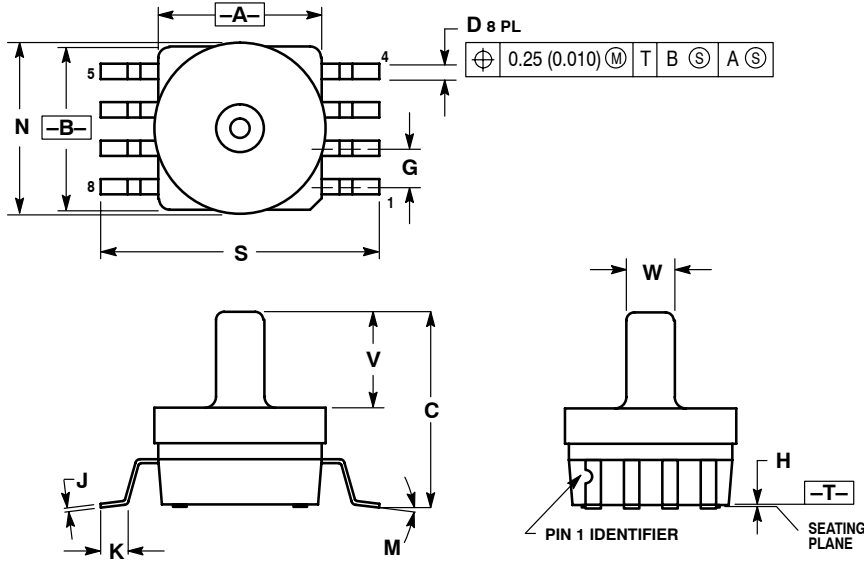


Figure 5. Small Outline Package Footprint

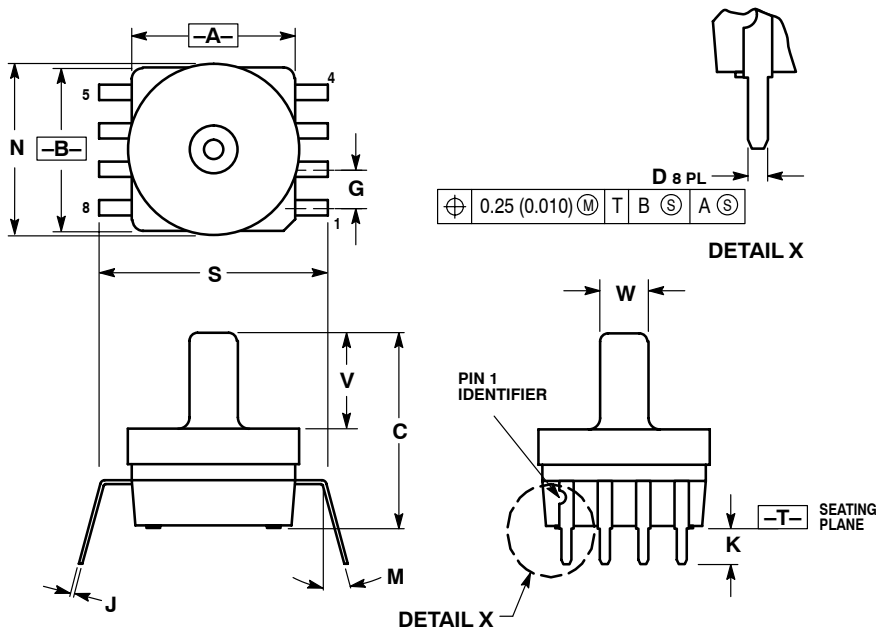
PACKAGE DIMENSIONS



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
  5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

| DIM | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
|     | MIN       | MAX   | MIN         | MAX   |
| A   | 0.415     | 0.425 | 10.54       | 10.79 |
| B   | 0.415     | 0.425 | 10.54       | 10.79 |
| C   | 0.500     | 0.520 | 12.70       | 13.21 |
| D   | 0.038     | 0.042 | 0.96        | 1.07  |
| G   | 0.100 BSC |       | 2.54 BSC    |       |
| H   | 0.002     | 0.010 | 0.05        | 0.25  |
| J   | 0.009     | 0.011 | 0.23        | 0.28  |
| K   | 0.061     | 0.071 | 1.55        | 1.80  |
| M   | 0°        | 7°    | 0°          | 7°    |
| N   | 0.444     | 0.448 | 11.28       | 11.38 |
| S   | 0.709     | 0.725 | 18.01       | 18.41 |
| V   | 0.245     | 0.255 | 6.22        | 6.48  |
| W   | 0.115     | 0.125 | 2.92        | 3.17  |

CASE 482A-01  
ISSUE A  
SMALL OUTLINE PACKAGE



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
  5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
  6. DIMENSION S TO CENTER OF LEAD WHEN FORMED PARALLEL.

| DIM | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
|     | MIN       | MAX   | MIN         | MAX   |
| A   | 0.415     | 0.425 | 10.54       | 10.79 |
| B   | 0.415     | 0.425 | 10.54       | 10.79 |
| C   | 0.500     | 0.520 | 12.70       | 13.21 |
| D   | 0.026     | 0.034 | 0.66        | 0.864 |
| G   | 0.100 BSC |       | 2.54 BSC    |       |
| J   | 0.009     | 0.011 | 0.23        | 0.28  |
| K   | 0.100     | 0.120 | 2.54        | 3.05  |
| M   | 0°        | 15°   | 0°          | 15°   |
| N   | 0.444     | 0.448 | 11.28       | 11.38 |
| S   | 0.540     | 0.560 | 13.72       | 14.22 |
| V   | 0.245     | 0.255 | 6.22        | 6.48  |
| W   | 0.115     | 0.125 | 2.92        | 3.17  |

CASE 482C-03  
ISSUE B  
SMALL OUTLINE PACKAGE

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